

2N5639

N-Channel Switch

- This device is designed for low level analog switchng, sample and hold circuits and chopper stabilized amplifiers.
- Sourced from process 51.



1. Drain 2. Source 3. Gate

Absolute Maximum Ratings * T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{DG}	Drain-Gate Voltage	30	V
V _{GS}	Gate-Source Voltage	-30	V
I _{GF}	Forward Gate Current	50	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	Off Characteristics					
V _{(BR)GSS}	Gate-Source Breakdown Voltage	$V_{DS} = 0, I_{G} = -10\mu A$ -30			V	
I _{GSS}	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$			-1.0	nA
I _{D(off)}	Drain Cutoff Leakage Current	$V_{DS} = 12V, V_{GS} = 15V$			1.0	nA
On Characteristics						
I _{DSS}	Zero-Gate Voltage Drain Current *	$V_{DS} = 20V, I_{GS} = 0$	25			mA
r _{DS(on)}	Drain-Source On Resistance	$V_{GS} = 0V, I_{D} = 1.0 \text{mA}$			60	Ω
Small Signal Characteristics						
r _{ds(on)}	Drain-Source On Resistance	$V_{DS} = V_{GS} = 0$, f = 1.0kHz			60	Ω
C _{iss}	Input Capacitance	$V_{DS} = 0$, $V_{GS} = 12V$, $f = 1.0MHz$			10	pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 0V, V_{GS} = 12V, f = 1.0MHz$			4.0	pF
Switching Characteristics						
t _{d(on)}	Trun On Delay Time	$V_{DD} = 10V, V_{GS(on)} = 0$			6.0	ns
t _r	Rise Time	$V_{GS(off)} = -12, I_{D(on)} = 12mA$			8.0	ns
t _{d(off)}	Trun Off Delay Time	$R_G = 50\Omega$		10	ns	
t _f	Fall Time	7			20	ns
Pulso Toet: Pulso Width < 200us Puty Cyclo < 1.0%						

^{*} Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1.0%

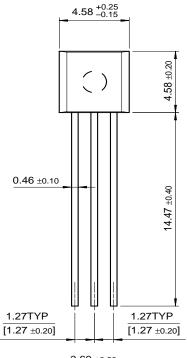
Thermal Characteristics T_A=25°C unless otherwise noted

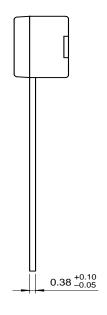
Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		°C/W

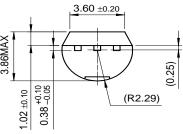
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Package Dimensions

TO-92







Dimensions in Millimeters

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